# Machined Board Stacking Strips

**Mates with:**
SS, SD, HSS, SL, SDL, ESS, ESD

## Features
- Low profile design achieves (3.89 mm) .153” board spacings when mated with SL Series.
- Approach the reliability of a permanent connection with the flexibility of a separable connection.

## Specifications

- **Insulator Material**:
  - Black Glass Filled Polyester (BBS, BBD, BBL)
  - Black High Temp Nylon (BDL)
  - Black Liquid Crystal Polymer (BHS)
- **Temperature Range**: -55°C to +125°C
- **Terminal Material**: Phosphor Bronze or Brass
- **Plating**: Au or Sn over 50µ” (1.27 µm) Ni
- **RoHS Compliant**: Yes
- **Lead-Free Solderable**: Wave only (BBS, BBD, BBL, BDL), Wave, or reflow with all Au (BHS)

## Recognitions
For complete scope of recognitions see www.samtec.com/quality

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**Note**: Some lengths, styles and options are non-standard, non-returnable.

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### Table: Types of Strips

<table>
<thead>
<tr>
<th>Type</th>
<th>Strip</th>
<th>No. of Pins Per Row</th>
<th>Plating Option</th>
<th>Lead Style</th>
<th>Note</th>
</tr>
</thead>
<tbody>
<tr>
<td>BBS</td>
<td>Standard Single Row</td>
<td>(2.54) .100 x No. of Positions</td>
<td>–G = 20 µ” (0.51 µm) Gold</td>
<td>–T = Tin</td>
<td>Low profile design achieves (3.89 mm) .153” board spacings when mated with SL Series.</td>
</tr>
<tr>
<td>BBL</td>
<td>Low Profile Single Row</td>
<td>(2.54) .100 x TYP</td>
<td></td>
<td></td>
<td>Approach the reliability of a permanent connection with the flexibility of a separable connection.</td>
</tr>
<tr>
<td>BHS</td>
<td>High Temp Single Row</td>
<td>(2.54) .100 x No. of Positions</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>BBD</td>
<td>Standard Double Row</td>
<td>(2.54) .100 x TYP</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>BDL</td>
<td>Low Profile Double Row</td>
<td>(3.18) .125</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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